

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BTS50015-1TAD	**Issued**	15. May 2021
MA#	MA004091350		
Package	PG-TO263-7-10	**Weight***	1555.16 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	11.254	0.72	0.72	7236	7236
chip_2	inorganic material	silicon	7440-21-3	1.848	0.12	0.12	1188	1188
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159	
	non noble metal	iron	7439-89-6	0.823	0.05		529	
	non noble metal	copper	7440-50-8	822.375	52.88	52.95	528805	529493
wire	non noble metal	aluminium	7429-90-5	13.765	0.89	0.89	8851	8851
encapsulation	inorganic material	zincoxide	1314-13-2	5.564	0.36		3577	
	miscellaneous	miscellaneous	-	22.254	1.43		14310	
	plastics	epoxy resin	-	83.453	5.37		53662	
	inorganic material	silicondioxide	60676-86-0	445.081	28.62	35.78	286196	357745
leadfinish	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7821	7821
plating	inorganic material	phosphorus	7723-14-0	0.007			5	
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1891	1896
solder	non noble metal	tin	7440-31-5	0.037			24	
	noble metal	silver	7440-22-4	0.046			30	
	non noble metal	lead	7439-92-1	1.763	0.11	0.11	1134	1188
glue	plastics	Polyimide	26023-21-2	0.781	0.05	0.05	502	502
heatspreader	inorganic material	phosphorus	7723-14-0	0.039			25	
	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	copper	7440-50-8	130.589	8.40	8.41	83971	84080
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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